an enclosure containing wafer engaging rollers, the wafer engaging rollers being oriented at an angle, the wafer engaging rollers designed to spin a wafer at an angle during preparation.

18. A wafer preparation module as recited in claim 17, wherein the preparation includes one of rinsing, cleaning, drying, scrubbing, and megasonic fluid application.

19. A wafer preparation module as recited in claim 17, further comprising:

at least one cleaner dispenser configured to apply a fluid to a surface of the wafer during at least part of the preparation.

20. A wafer preparation module as recited in claim 17, further comprising:

a nozzle configured to apply a gas flow toward at least one of wafer engaging rollers.

21. A wafer preparation module as recited in claim 17, further comprising:

a megasonic spray assembly for applying a megasonic spray to a surface of the wafer.

22. A wafer preparation module as recited in claim 17, wherein at least one of the wafer engaging rollers is a drive roller.

23. A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed; and

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle.

24. **(Amended)** A spin, rinse, and dry module as recited in claim 23, further comprising:

a cleaner dispenser defined within the enclosure, the cleaner dispenser being configured to clean a top surface and a bottom surface of the substrate to be processed.

25. A spin, rinse, and dry module as recited in claim 23, further comprising:

a megasonic assembly defined within the enclosure, the megasonic assembly being configured to be applied to a top surface and a bottom surface of the substrate to be processed.

26. **(Amended)** A spin, rinse, and dry module as recited in claim 23, further comprising:

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a plurality of gas blow nozzles defined within an inner wall of the enclosure, at least one gas blow nozzle being configured to dispense a first gas onto each of the drive rollers and the engaging roller.

27. A spin, rinse, and dry module as recited in claim 23, further comprising:

a plurality of holes defined within an inner wall of the enclosure so as to introduce a second gas into the enclosure, the second gas being configured to substantially evenly dry a top surface and a bottom surface of the substrate to be processed.

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28. **(New)** A wafer preparation module, comprising:

an enclosure containing wafer engaging rollers, the wafer engaging rollers being oriented at an angle, the wafer engaging rollers designed to spin a wafer at an angle during preparation; and

a nozzle configured to apply a gas flow toward at least one of wafer engaging rollers.

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29. **(New)** A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed;

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers

configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

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a plurality of gas blow nozzles defined within an inner wall of the enclosure, at least one gas blow nozzle being configured to dispense a first gas onto each of the drive rollers and the engaging roller.

30. **(New)** A spin, rinse, and dry module comprising:

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an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed;

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

a plurality of holes defined within an inner wall of the enclosure so as to introduce a second gas into the enclosure, the second gas being configured to substantially evenly dry a top surface and a bottom surface of the substrate to be processed.

31. **(New)** A wafer preparation module, comprising: